

## GenX3™ 1200V IGBTs

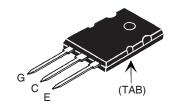
# IXGK120N120B3 IXGX120N120B3

High Speed Low Vsat PT IGBTs for 3-20 kHz Switching

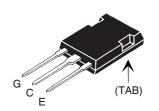


$\mathbf{V}_{CES}$	=	1200V
I <sub>C90</sub>	=	120A
V <sub>CE(sat)</sub>	≤	3.0V

TO-264 (IXGK)



PLUS 247™ (IXGX)



G	= Gate	E	=	Emitter
C	= Collector	TAB	=	Collector

### Features

- Optimized for Low Conduction and Switching Losses
- Square RBSOA
- International Standard Packages

### **Advantages**

- High Power Density
- Low Gate Drive Requirement

#### **Applications**

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions	Maximum F	Ratings
V <sub>CES</sub>	T <sub>J</sub> = 25°C to 150°C	1200	V
V <sub>CGR</sub>	$T_{_{\mathrm{J}}}$ = 25°C to 150°C, $R_{_{\mathrm{GE}}}$ = 1M $\Omega$	1200	V
V <sub>GES</sub>	Continuous	±20	V
V <sub>GEM</sub>	Transient	±30	V
I <sub>C25</sub>	T <sub>c</sub> = 25°C ( Chip Capability )	200	A
I <sub>C90</sub>	$T_{\rm c} = 90^{\circ}$ C	120	Α
LRMS	Terminal Current Limit	120	Α
I <sub>CM</sub>	$T_{c} = 25^{\circ}C$ , 1ms	370	Α
SSOA	$V_{GE} = 15V, T_{VJ} = 125^{\circ}C, R_{G} = 2\Omega$	I <sub>CM</sub> = 240	A
(RBSOA)	Clamped Inductive Load	$V_{CES} \le 1200$	V
P <sub>c</sub>	T <sub>c</sub> = 25°C	830	W
T		-55 +150	°C
$T_{JM}$		150	°C
T <sub>stg</sub>		-55 +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering	300	°C
T <sub>SOLD</sub>	1.6 mm (0.062 in.) from Case for 10	260	°C
M <sub>d</sub>	Mounting Torque ( IXGK )	1.13/10	Nm/lb.in.
F <sub>c</sub>	Mounting Force (IXGX)	20120/4.527	N/lb.
Weight	TO-264	10	g
	PLUS247	6	g

<b>Symbol</b> $(T_J = 25^{\circ}C, U)$	<b>Test Conditions</b> Unless Otherwise Specified)	Chara Min.	cteristic '	Values   Max.	
BV <sub>CES</sub>	$I_{C} = 250 \mu A, V_{CE} = 0 V$	1200			V
V <sub>GE(th)</sub>	$I_{\rm C} = 1  \rm mA, \ V_{\rm CE} = V_{\rm GE}$	3.0		5.0	V
I <sub>CES</sub>	$V_{CE} = V_{CES, V_{GE}} = 0V$	T <sub>J</sub> = 125°C		1	μA mA
I <sub>GES</sub>	$V_{CE} = 0V, V_{GE} = \pm 20V$			±400	nA
V <sub>CE(sat)</sub>	$I_{\rm C}=100$ A, $V_{\rm GE}=15$ V, Note	÷ 1	2.4	3.0	V



Symbol (T <sub>J</sub> = 25°C, U	Test Conditions Unless Otherwise Specified)	Char Min.	acteristic Typ.	Values Max.
g <sub>fs</sub>	I <sub>C</sub> = 60A, V <sub>CE</sub> = 10V, Note 1	40	70	S
C <sub>ies</sub>			9700	pF
C <sub>oes</sub>	$V_{CE} = 25V$ , $V_{GE} = 0V$ , $f = 1 MHz$		670	pF
C <sub>res</sub>			255	pF
$Q_{g(on)}$			470	nC
$Q_{ge}$	$I_{C} = I_{C90}, V_{GE} = 15V, V_{CE} = 0.5 \bullet V_{CES}$		67	nC
Q <sub>gc</sub>			190	nC
t <sub>d(on)</sub>			36	ns
t <sub>ri</sub>	Inductive load, T <sub>J</sub> = 25°C		88	ns
E <sub>on</sub>	$I_{\rm C} = 100A, V_{\rm GE} = 15V$		5.5	mJ
t <sub>d(off)</sub>	$V_{CE} = 600V, R_{G} = 2\Omega$		275	ns
t <sub>fi</sub>	Note 2		145	ns
E <sub>off</sub>			5.8	mJ
t <sub>d(on)</sub>			34	ns
t <sub>ri</sub>	Inductive load, T <sub>J</sub> = 125°C		88	ns
E <sub>on</sub>	$I_{\rm C} = 100A, V_{\rm GE} = 15V$		6.1	mJ
t <sub>d(off)</sub>	$V_{CE} = 600V$ , $R_{G} = 2\Omega$		315	ns
t <sub>fi</sub>	Note 2		570	ns
E <sub>off</sub>			10.3	mJ
R <sub>thJC</sub>				0.15 °C/W
R <sub>thCK</sub>			0.15	°C/W

TO-264 (IXGK) Outline					
TO-264 (IXGK) Outline  TO-264 (IXGK) Outline  BACK SDE  BACK SDE  A  BACK SDE  B					
-		URCE (ÉM			,
SYM	MIN	MAX	MILLIM	MAX	-
A	.185	.209	4.70	5.31	1
A1	.102	.118	2.59	3.00	1
b	.037	.055	0.94	1.40	1
b1	.087	.102	2.21	2.59	1
b2	.110	.126	2.79	3.20	1
C	.017	.029	0.43	0.74	]
D	1.007	1.047	25.58	26.59	
E	.760	.799	19.30	20.29	]
e	.215		5.46		
J	.000	.010	0.00	0.25	]
K	.000	.010	0.00	0.25	
L	.779	.842	19.79	21.39	]
L1	.087	.102	2.21	2.59	]
ØP	.122	.138	3.10	3.51	]
Q	.240	.256	6.10	6.50	1
Q1	.330	.346	8.38	8.79	1
ØR	.155	.187	3.94	4.75	]
ØR1	.085	.093	2.16	2.36	]
S	.243	.253	6.17	6.43	]

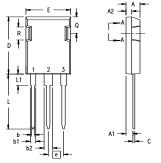
#### Note

- 1. Pulse Test,  $t \le 300\mu s$ , Duty Cycle,  $d \le 2\%$ .
- 2. Switching Times may Increase for  $V_{CE}$  (Clamp) > 0.8  $V_{CES}$ , Higher T<sub>1</sub> or Increased R<sub>6</sub>.

#### **ADVANCE TECHNICAL INFORMATION**

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

## PLUS 247™ (IXGX) Outline



Terminals: 1 - Gate

2 - Drain (Collector) 3 - Source (Emitter)

Dim.	Millimeter		Inc	hes
	Min.	Max.	Min.	Max.
Α	4.83	5.21	.190	.205
$A_1$	2.29	2.54	.090	.100
$A_2$	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b,	1.91	2.13	.075	.084
$b_2$	2.92	3.12	.115	.123
С	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
Е	15.75	16.13	.620	.635
е	5.45 BSC		.215	BSC
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	0.244
R	4.32	4.83	.170	.190

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